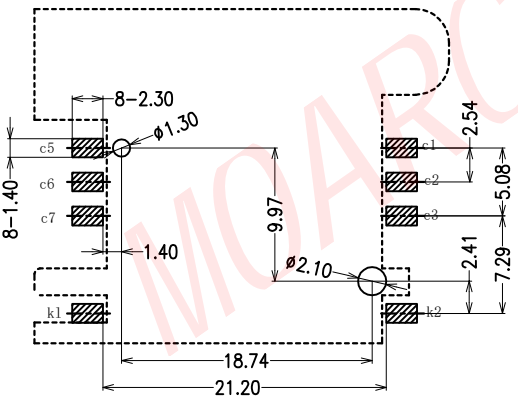
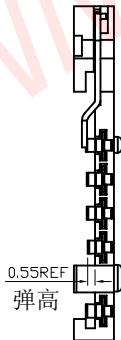
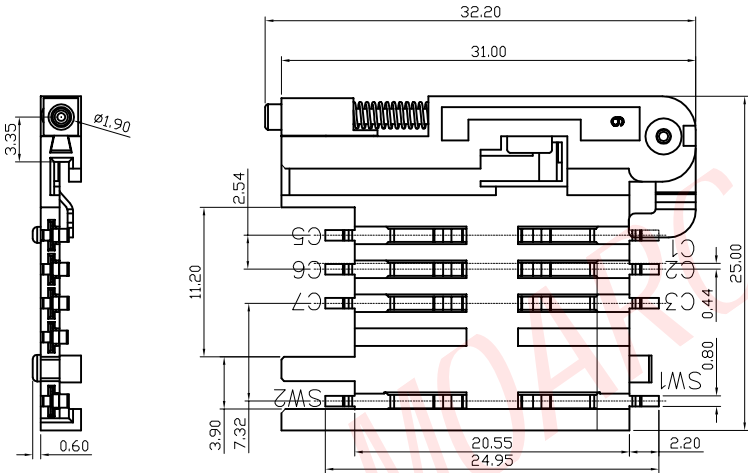
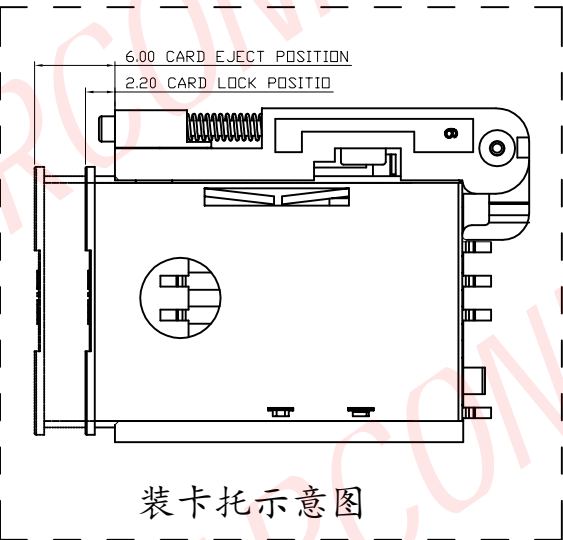
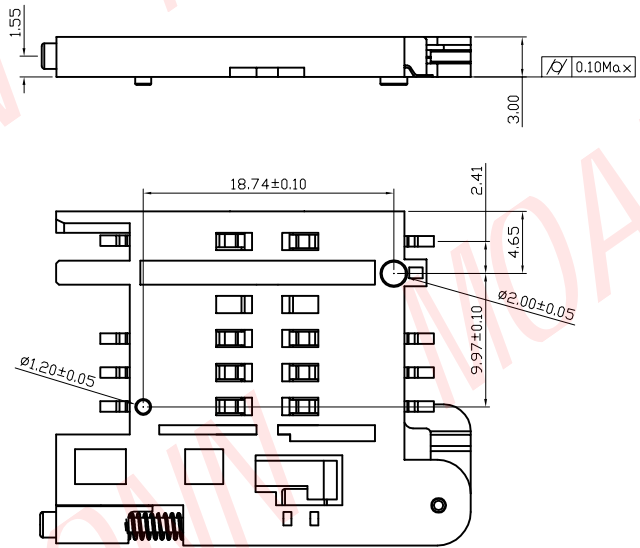


All materials, plating and process meet HF requirements.



PCB AREA
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



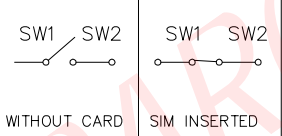
Specification

MATERIAL:
Insulator: High Temperature Thermoplastic,
COVER: PA9T UL 94V-0 Yellow
Contact: Copper Alloy(铜) T=0.15mm

PLATING:
Contact: Plated 50u'' Ni Overall Contact Au G/F, pad TIN

Electrical:
Current Rating :2Amps.max
Voltage Rating :5V AC/DC
Ambient Temperature Range :-40° C~+85° C
Storage Temperature Range :-40° C~+85° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩmax.
Insulation Resistance:1000MΩmin.
Mating Cycles:5000Min Insertions

PIN NO.	PIN NAME
	Supply Voltage Vcc
C2	Reset (RST)
C3	Clock (CLK)
C4	N/A
C5	Ground
C6	Programming Voltage Vpp
C7	I/O
C8	N/A



REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X1	---	RELEASE	Aaron	2024.06.20
X0	---	NEW RELEASE	Aaron	2022.10.19

MOARCONN
MORE CONNECTIONS SMART FUTURE

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2'

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

PRODUCT NAME : SIM CARD CONN. WITH TRAY TYPE	DRAWING: Aaron	DATE: 2024.06.20
PRODUCT NO. : KF016-L0012-32	CHECK:	DATE:
DRAWING NO. : D-KF016-L0012-32	APPROVED:	DATE:
SCALE: 1:1	DWG ID: C D	REV.: X1
		PAGE: 1 of 1